

#3

DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: **Physical Vapor Deposition Targets, Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, And Metal Alloys For Use As A Conductive Interconnection In An Integrated Circuit**, Serial No. 09/449,025, filed November 24, 1999.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under

1 Section 1001 of Title 18 of the United States Code and that such willful
2 false statement may jeopardize the validity of the application or any
3 patent issued therefrom.

4 * * * * *

5 Full name of inventor: **Shozo Nagano**

6 Inventor's Signature: _____

7 Date: _____

8 Residence: **Kanagawa, Japan**

9 Citizenship: **Japanese**

10 Post Office Address: **1-3-5-405 Mizuhiki Atsugi**
11 **Kanagawa, Japan 234-004**

12 * * * * *

13 Full name of inventor: **Hinrich Hargarter**

14 Inventor's Signature: _____

15 Date: _____

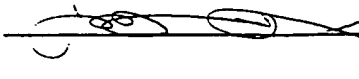
16 Residence: **The Netherlands**

17 Citizenship: **German**

18 Post Office Address: **P.O. Box 10000**
19 **1970 CA IJmuiden**
20 **The Netherlands**

* * * * *

Full name of inventor: **Jianxing Li**

Inventor's Signature: 

Date: 4/27/00


Residence: **Spokane, Washington**

Citizenship: **Chinese**

Post Office Address: **4908 N. Calvin Road
Spokane, WA 99216**

* * * * *

Full name of inventor: **Jane Buehler**

Inventor's Signature: 

Date: 04/27/00

Residence: **Spokane, Washington**

Citizenship: **U.S.**

Post Office Address: **18517 E. Norman Ridge Lane
Spokane, WA 99217**



DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: **Physical Vapor Deposition Targets, Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, And Metal Alloys For Use As A Conductive Interconnection In An Integrated Circuit**, Serial No. 09/449,025, filed November 24, 1999.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under

1 Section 1001 of Title 18 of the United States Code and that such willful
2 false statement may jeopardize the validity of the application or any
3 patent issued therefrom.

4 * * * * *

5 Full name of inventor: Shozo Nagano

6 Inventor's Signature: _____

7 Date: _____

8 Residence: Kanagawa, Japan

9 Citizenship: Japanese

10 Post Office Address: 1-3-5-405 Mizuhiki Atsugi
11 Kanagawa, Japan 234-004

12 * * * * *

13 Full name of inventor: Hinrich Hargarter

14 Inventor's Signature: Hinrich Hargarter

15 Date: 02-15-00

16 Residence: The Netherlands

17 Citizenship: German

18 Post Office Address: P.O. Box 10000
19 1970 CA IJmuiden
20 The Netherlands
21
22
23
24

1
2
3
4
5
6
7
8
9
10
11
12
13
14
15
16
17
18
19
20
21
22
23
24

* * * * *

Full name of inventor: Jianxing Li

Inventor's Signature: _____

Date: _____

Residence: Spokane, Washington

Citizenship: Chinese

Post Office Address: 4908 N. Calvin Road
Spokane, WA 99216

* * * * *

Full name of inventor: Jane Buehler

Inventor's Signature: _____

Date: _____

Residence: Spokane, Washington

Citizenship: U.S.

Post Office Address: 18517 E. Norman Ridge Lane
Spokane, WA 99217



DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: **Physical Vapor Deposition Targets, Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes, And Metal Alloys For Use As A Conductive Interconnection In An Integrated Circuit**, Serial No. 09/449,025, filed November 24, 1999.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under

1 Section 1001 of Title 18 of the United States Code and that such willful
2 false statement may jeopardize the validity of the application or any
3 patent issued therefrom.

4 * * * * *

5 Full name of inventor: Shozo Nagano

6 Inventor's Signature: Shozo Nagano

7 Date: 2/1/2000

8 Residence: Kanagawa, Japan

9 Citizenship: Japanese

10 Post Office Address: 1-3-5-405 Mizuhiki Atsugi
11 Kanagawa, ~~Japan 234-004~~
243-0004 Japan

12 * * * * *

13 Full name of inventor: Hinrich Hargarter

14 Inventor's Signature: _____

15 Date: _____

16 Residence: The Netherlands

17 Citizenship: German

18 Post Office Address: P.O. Box 10000
19 1970 CA IJmuiden
The Netherlands

* * * * *

Full name of inventor: **Jianxing Li**

Inventor's Signature: _____

Date: _____

Residence: **Spokane, Washington**

Citizenship: **Chinese**

Post Office Address: **4908 N. Calvin Road
Spokane, WA 99216**

* * * * *

Full name of inventor: **Jane Buehler**

Inventor's Signature: _____

Date: _____

Residence: **Spokane, Washington**

Citizenship: **U.S.**

Post Office Address: **18517 E. Norman Ridge Lane
Spokane, WA 99217**